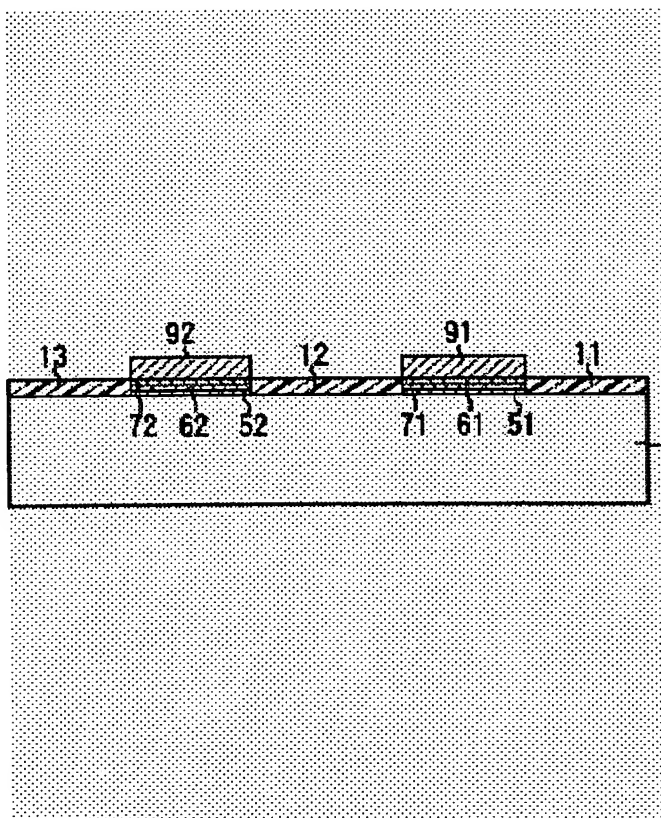


BOARD MOUNTED WITH PART, METHOD FOR MANUFACTURING BOARD MOUNTED WITH ELECTRONIC PART DEVICE AND PART, AND METHOD FOR MOUNTING CHIP PART

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Abstract of JP2001189552

PROBLEM TO BE SOLVED: To provide a board mounted with a part, a method for manufacturing a board mounted with electronic part devices and parts, and a method for mounting a chip part, capable of preventing a solder metal component from oozing out.
SOLUTION: Metal films 51-71, 52-72 are deposited on the mounting surface of a substrate 1. Protective films 12-13 are attached to the mounting surface of the substrate 1 to bury a space produced around the metal films 51-71, 52-72. Solder metal films 91, 92 are deposited on the surfaces of the metal films 51-71, 52-72 to make the almost the whole surface a flat surface nearly parallel to the mounting surface of the substrate 1.



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